

IN THE CLAIMS

Please amend the claims as follows:

Claims 1-6 (Canceled).

Claim 7 (New): A method of manufacturing an electronic part including plural wiring patterns and an insulating layer interposed between the wiring patterns and in which electrical connection between the wiring patterns is established through an interlayer connecting portion that penetrates the insulating layer, the method comprising:

a first step of forming the wiring pattern and a columnar conductor;

a second step of bonding an insulating sheet from an upper side thereof, pressing the insulating sheet to a height of the columnar conductor with the columnar conductor as a stopper, and conforming a thickness of the sheet to the height of the columnar conductor to form a layer having a uniform thickness; and

a third step of removing a cover layer from a surface of the layer, which is formed in the second step, through a chemical reaction, and exposing an uneven pattern for increasing an adhesion strength between the wiring pattern and the columnar conductor;

wherein the columnar conductor, which determines a thickness of the layer, is used as the interlayer connecting portion and particles having a spacer function are mixed into the insulating sheet, and the particles are sandwiched between the columnar conductor and the cover layer in the second step to form a thin film insulating layer on an upper surface of the columnar conductor.

Claim 8 (New): A method of manufacturing an electronic part according to claim 7, wherein a thickness of the thin film insulating layer is between 1 to 15 μm .

Claim 9 (New): An electronic part according to claim 7, wherein the columnar conductor is formed by a metal plating method.